

S-TAKAYA
ELECTRONICS INDUSTRY CO.,LTD.

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Check our website for details

<https://www.s-takaya.co.jp/en>

S-TAKAYA

Search



(2024.7)



Contribute to the **Future of Society**

With our unique **tech nology** and **know-how**,
we utilize forefro nt technology and
contribute to the **future** of society.

"S" co ntains

The "S" included in the company name has various meanings and it is reflecting the era of diversity.
Here, we Start such company.



SATOSHO



SURPRISE



SMART



SPECIAL



SEEK



SPICES



SMILE



SCOOP

August 1979 —→ **October 2021**

Renamed and reborn as "S-TAKAYA ELECTRONICS INDUSTRY CO.,LTD."

Business

Our Business

We develop unique LSI device and modules and build production system

We, S-TAKAYA, have been contributing ourselves to the development of information society through the development and manufacturing of LSI (Large Scale Integrated Circuit) device and module.

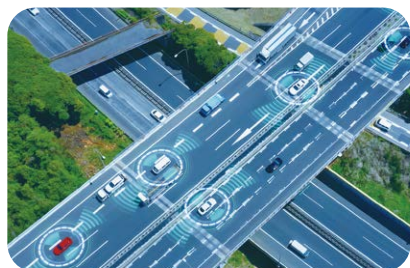
In the growing society, the requirements of the customer is diversifying. We continue creating and providing wide variety of solutions by such as manufacturing unique LSI device and products, building production system and manufacturing customized equipment and jigs.

SERVICE



LSI device and module

We manufacture and inspect various types of modules including in-vehicle, medical and smart phones, and also, we manufacture packages such as BGA, COF, Image sensors.



Radar module

We provide customized offer from design and development of radar module to mass production according to the needs and environment of the customers.



Development of automation equipment

We will propose the most suitable solution for your manufacturing needs. If you are looking for automation, labor saving, miniaturization, R&D and ODM support, Please feel free to contact us.



Environmental products

We offer product and services which are environmental friendly.

Reason

Why S-TAKAYA is selected

Keep satisfying customer needs

We satisfy the customer requirements with our manufacturing technology and know-how for various semiconductor assemblies which has been developed with more than 40 years history since the establishment.



LSI Device Module Large Scale Integration

We support our customers with sufficient experience and technical capabilities which meet various needs.

With the dramatic evolution of electronics, LSI device and module are required to have higher functionality with downsizing. We, in order to meet these market demands, are producing latest LSI device and module by integrating technologies, equipment and systems with installing newest equipment and building efficient production system.

Production System

We can offer one-stop support from wafer testing to module mounting. With our unique technology, we support the customer to build the required production system.

01 Request



We make products according to requirements of the customer. Please feel free to contact us.

02 Wafer test



Wafer test of the product.

03 Polishing / Dicing



Backside polishing, laser grooving, Wafer dicing.

04 Post-process assembly of LSI device

● Die bonding

● Wire bonding / Bump bonding

● Flip chip bonding

● Molding

Assemble with our unique technology.

05 Module mounting



Check the product through mounting process.

06 Final test/ Appearance check



Test before delivery. Detailed check of the performance.

07 Delivery



We support one-stop service from request to delivery.

OP1 Analysis service


OP2 Reliability tests

Product lineup


 Camera module
Image sensor

 Module/MCM

 COF
(Chip On Film)

 BGA (Ball Grid Array)/
Plastic package


 Special molding
(Transparent plastic mold)


 Special molding
(Partially exposed mold)

 Special molding
(Premolded hollow package)

 Wire bump, dicing
and automatic
measuring inspection

 TAIKO® wafer rib
removal, dicing

 Chip full test

 6-side visual inspection for all chips and
KGD (Known Good Die)

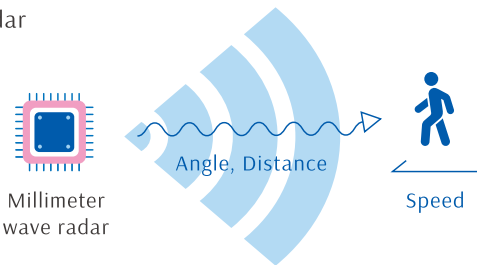
Radarmodule Millimeter Wave Radar

Our technical capability makes one-stop support from development to mass production possible.

We support everything from designing, developing to mass production of radar modules which meet requirements of the customer.


Advantage of radar

The millimeter wave at the frequency of 30GHz – 300GHz has a strong straightness characteristic that it has less affects from external environmental factors such as rain and fog. The device which uses this millimeter wave for sensing is called millimeter wave radar. With millimeter radar, it is possible to obtain the data of distance, angle and speed of the object.




	Radar	Infrared	Ultrasound	Camera	LIDAR
Short distance detection (2m or less)	●	●	●	●	●
Medium distance detection (2-30m)	●	●		●	●
Long distance detection (more than 30m)	●				●
Distance detection	●	●		●	●
Speed detection	●		●		●
Angle detection	●	●		●	●
Environmental resistance	●				
Freedom of product design	●				
Size	●	●	●	●	
Price	●	●	●	●	


Where millimeter wave radar can be used?

 **Anti-crime measure**


It can be applied as an anti-crime measure, as it detects the intrusion of suspicious person by identifying the distance and angle.

 **Safety detection**

It can detect sudden illnesses and abnormalities while considering the privacy, in the places which installing camera would be difficult such as toilet and bathroom.

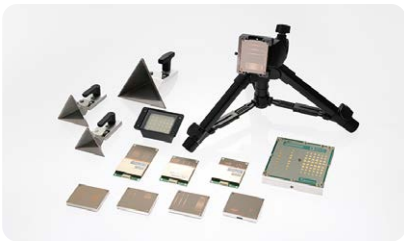
 **Monitoring of babies and nursing-care places**

It can identify the changes in medical condition by detecting the breath and pulse on the bed, and thus, it can prevent the accidents such as suffocation.

 **Energy-saving device**

Through the combination with lights and home appliances, it can be applied as energy-saving device as the radar enables automatic control of the power supply via detecting human activities.

About Evaluation kit



It is possible to immediately start evaluating your radar module with the evaluation kit. By extracting the issues using the evaluation kit, it is possible to reduce the cost for trial production and evaluation.

Evaluation kit series

Series	MMIC	Frequency	Distance	Speed	Angle	MP※1
ST24ZS2 SERIES	Infineon Technologies	24GHz	●			▲
T14RE SERIES	Texas Instruments	79GHz	●	●	●	●
T68PE SERIES	Texas Instruments	60GHz	●	●	●	●
T68PE2 SERIES	Texas Instruments	60GHz	●	●	●	●
T18PE SERIES	Texas Instruments	76GHz, 79GHz	●	●	●	●
Atlas24 SERIES	Analog Devices	24GHz	●	●	●	▲
Atlas7xG SERIES	Analog Devices	76GHz, 79GHz	●	●	●	▲
Eris SERIES	NXP Semiconductors	79GHz	●	●	●	▲
Eris2 SERIES	NXP Semiconductors	76GHz, 79GHz	●	●	●	▲
Athena60 SERIES	Asahi Kasei Microdevices Corporation	60GHz	●	●	●	●
Athena79 SERIES	Asahi Kasei Microdevices Corporation	79GHz	●	●	●	▲

※1 ▲ = With customization, MP is available

Facility & Original product

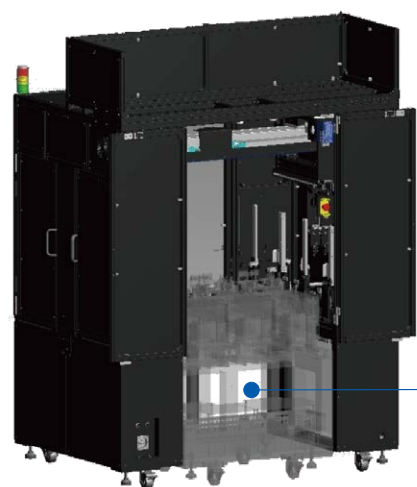
Development of automation equipment

We contribute to the innovation at manufacturing sites.

With our enriched experience in the semiconductor industry, we provide the best solution for automation in your manufacturing site.

Customized test handler DX series

This is a fully automatic test handler with a structure in which the transport unit and the inspection unit are separated. We can also offer various test units according to the inspection contents of the camera module.



Actual examples of the test unit adoption

We customize the test unit according to the work and inspection environment of the customer.

DX1327

For the stroke behavior measurement of camera module
 ● 3 Stage (6dut) type
 ● Test unit
 VCM stroke inspection / OIS (optical image stabilization) characteristic inspection



DX1533

For the downward characteristic inspection of camera module
 ● 3 Stage (6dut) type
 ● Test unit
 infinity characteristic inspection / black scratch inspection / white scratch inspection



DX2299

For ultra wide-angle camera module
 ● 2 Stage (4dut) type
 ● Test unit
 Optical center inspection / black scratch inspection



Characteristics

- It is possible to configure the test unit according to various objects and inspection contents.
- The other packages would be proposed after consultation.
(CSP / BGA / QFN / QFP, etc.)
- Standardized object conveying section
- Handler shape W1760 x D1230 x H2280 (mm)
- Test unit dimension: W 940 x D700 x H1000 (mm)
- Processing capacity: 300 - 500 (UPH)
*This varies depending on the test unit and inspection details.

Other equipment



Camera module fully automatic tester



General-purpose loader / unloader



Laser solder mounting equipment



Inline multifunction resin coating machine

Environmental

Environmental Products

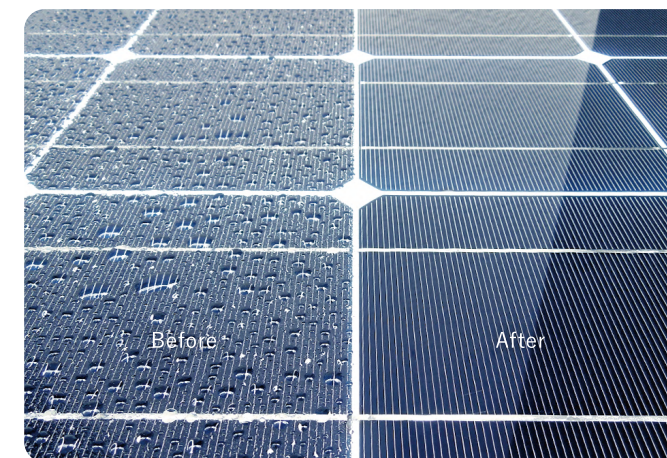
We propose what we can do in order to leave “beautiful earth” for the future.

Solar Panel Cleaning



Iron Remover (Iron Remover for solar panels)

Iron Remover efficiently removes the iron powders accumulated on solar panels.



PV Hydro Coat (Coating for solar panels)

PV Hydro Coat prevents the decrease in power generation from dirt accumulation on solar panel surface by utilizing rain power utmost.



PV Scale Remover

The cleaning agent is used to remove scales that are adhered on solar panels and stains that are a mixture of iron powder and minerals.



PV SP Cleaner

A cleaning agent that removes organic dirt such as tree sap, pollen, bird droppings, and soot.



Sustainability

Our Activities

We achieve the carbon neutrality through environmental friendly manufacturing.

Activities on SDGs

01 Be friendly to the earth



We engage ourselves in zero emission based on ISO14001 (certified for 20 years) by building a process with minimized environmental impact, from material selection to manufacturing process and disposal.

02 To an affluent society



We contribute ourselves to an affluent information society through manufacturing various module products based on our technology with over 40 years history which is capable to fit into this diversifying era.

03 To a safe and secure society



We contribute ourselves to a safe and secure society by developing and utilizing the module products which can be applied on various human lives such as medical care, disaster prevention and vehicles.

Activities on CSR

At S-TAKAYA, under our company motto and mission statement, all employees adhere to the code of behavior of company and employees, and promote healthy business activities, in order to contribute to the sustainable development of society. To achieve this, we enhance our company value by not only complying the law, but also fulfilling our social responsibilities as a good corporate citizen and establish trust with all the related parties.

In CSR activities of S-TAKAYA, following global guidelines and principles are referred.
Industrial code of behavior such as ISO26000 (Global guidelines for corporate social responsibility) / JIS Z26000 "Guidance of Social Responsibility / SDGs "Sustainable Development Goals" / RBA (Responsible Business Alliance)

Policies

Environmental Policy

As S-TAKAYA develops, designs, manufactures and sells semiconductors, electrical machines and related products, it is our responsibility to manufacture products which are friendly to the environment of the earth. We put efforts on environmental preservation activities based on our behavioral guidelines and basic environmental philosophy.

Quality Policy

"Quality First in Heart and Mind"

Information security policy

S-TAKAYA is, located in Okayama prefecture where has less natural disasters, manufacturing and inspecting IC and LSI device products with various packages. Also, we develop, manufacture and sell our unique products and electrical and electronic equipment by utilizing our know-how built over many years. In our business, the information needs to be securely dealt with at daily basis, and especially, it is essential to strengthen the information security management for production management system, customer information and technology information. In order to continue contributing ourselves to the development of information society through development and manufacturing of semiconductor device products, we introduce ISMS and practice highly secure management, and adhere to following policy for our continuous improvement.



04 Creating an attractive workplace

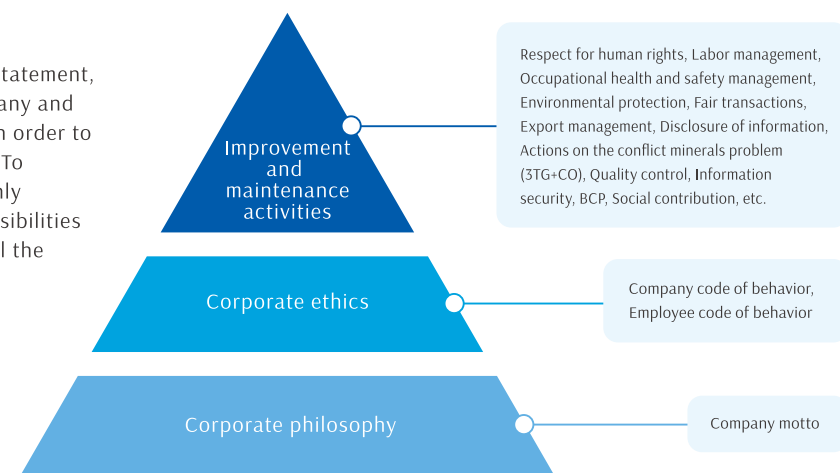


We create and develop an attractive workplace by guaranteeing a healthy working environment and system, providing skill improvement opportunities to the employees, and promoting the work style reform.

05 Contributing to the community



We contribute ourselves to achieve a sustainable regional community by continuing our activities on active recruitment of local people, collaboration with local business parties and efforts on local volunteer work.



Company

Company profile

Greeting from our president

Build a rich life, create an attractive workplace, and aim for a comfortable society

Since our establishment in 1979, with these motto and mission statement, we have been contributing to the sustainable development of the society as a manufacturer of LSI devices and modules. In the early 2000s, with the accelerated globalization of the domestic manufacturers, we expanded our business area to overseas. With our technological capabilities obtained in many years experience, we developed our company as a manufacturer of the world's highest level camera modules. As a result, we have been successfully developing the collaborative business relationship with leading companies in domestic and overseas market. The environment around our manufacturing industry has been facing difficulties, however, we believe that the importance of "Made in Japan" will be reaffirmed and the time will surely come. We will continue emphasizing "Quality First", and grow our reliability and company value with the diversity management. This aims to improve our competitiveness, achieve an ideal company, and toward mutual growth with all stakeholders. Our company, with all the employees, continue growing by valuing this business spirit, and we keep developing our business multidirectionally with willingness to take a challenge to new era and requirement.

Futoshi YUNOKI, President and CEO

Company Profile



Headquarters

- Company Name
S-TAKAYA ELECTRONICS INDUSTRY CO.,LTD.
- Establishment
August 15, 1979
- President / CEO
Futoshi YUNOKI
- Capital
JPY100 million
- Employee
555 (As of April 2024)
- Sales Revenue
9.71 billion yen (Fiscal year 2023)
- Product and Service
Development, sales and manufacturing of semiconductor device, module products and automation equipment. Designing, development and manufacturing of radar modules.
- Location
3121-1 Satomi Satoshio-cho, Asakuchi-gun, Okayama, 719-0301, JAPAN
TEL: +81-865-64-4131
FAX: +81-865-64-4474



Related Company

- Company Name
SAIGON STEC CO.,LTD.
- Establishment
September 2007
- Capital
Capital USD6,100,000 (Sharp Corporation 51%, S-TAKAYA ELECTRONICS INDUSTRY CO.,LTD. 49%)
- Product and Service
Camera module assembly / inspection
- Location
Binh Duong Province VSPIII Industrial Complex, Socialist Republic of Vietnam
TEL: +84-274-363-5290
FAX: +84-274-363-5295



History

1979

1979	Aug.	Establishment, Capital JPY250 million yen
1980	Apr.	Started IC/LSI package assembly & test
1981	Jun.	Increased capital to JPY280 million yen
	Dec.	Started Wafer test
1983	Mar.	Completed 2nd building construction and started operation
	Apr.	Started TCP process production
1984	Jun.	Increased capital to JPY300 million
1985	Apr.	Started COB process production
1988	May.	Started Chip production
1989	May.	Completed 3rd building construction and started operation

1989

1990

1991	Jan.	Completed 4th building construction and started operation
	Apr.	Certified RCJ, Registered electronic component certification
1992	Oct.	Started production of CCD process
1993	Jul.	Acquired ISO9001 certification
1996	Aug.	Started CSP process production
1997	Feb.	Started wafer polishing on back surface
1998	Nov.	Started SOF production
1999	Sep.	Acquired ISO14001 certification

1999

2000

2000	Jun.	Increased capital to JPY310 million yen
	Aug.	Completed 5th building construction and started operation
2001	Oct.	Started camera module production
2002	Nov.	Started IC card production
2003	May.	Development Technology Center (former Yakage Factory) started operation
2006	Mar.	Started One-Seg module production
2007	Sep.	Started CSP production at wafer level
2008	Aug.	SAIGON STEC (100% subsidiary) started operation
	Oct.	Started Camera unit production
2009	Mar.	Started solar module production
		Acquired ISO27001 certification

2009

2010

2012	Oct.	Started touch panel module assembly production
2014	Jun.	Started operation of solar power plant in Yakage
2015	May.	Started operation of solar power plant at headquarters
	Sep.	Ended production of IC card
	Oct.	Acquired ISO / TS16949 certification
2018	May.	Transferred 51% share of SAIGON STEC to SHARP Corporation
2019	Jul.	Started Radar module production
2020	Mar.	Received all of SHARP TAKAYA share from SHARP Corporation
	Jun.	Changed the capital to JPY100 million yen
2021	Mar.	Integrated the Development Technology Center (former Yakage Factory) into head office and returned to TAKAYA Corporation
	Jun.	Registered as a medical device manufacturer
	Oct.	Renamed the company name to "S-TAKAYA ELECTRONICS INDUSTRY CO.,LTD." from "SHARP TAKAYA ELECTRONICS INDUSTRY CO.,LTD."
2022	Dec.	Discontinued production of mold packages (lead frame products)
2023	Aug.	Certified as a Kyu (救) mark certified company from Kasaoka District Fire Union
2024	Jan.	Sports Yell Company 2024 certification
	Mar.	Certified as a 2024 KENKO Investment for Health Outstanding Organization (large enterprise category)
	May.	Started Power semiconductor production